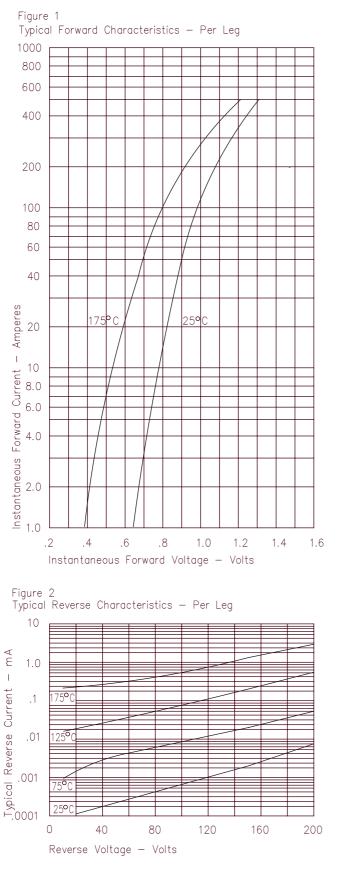
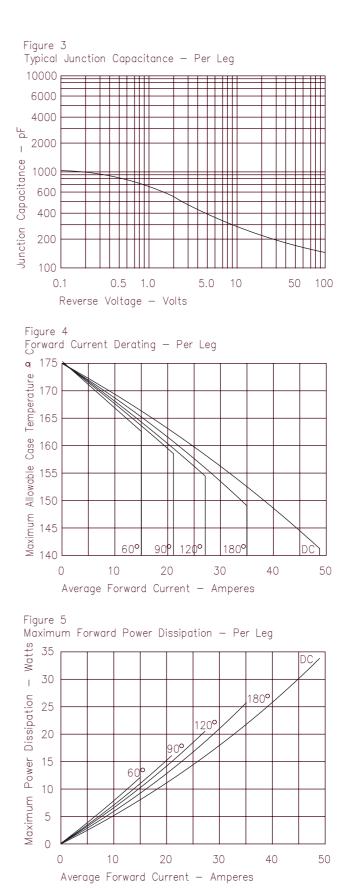
Liltrafact Decove		
Ultrafast Recove	$1 \ 2 \ 7 \ 7 \ 7 \ 7 \ 7 \ 7 \ 7 \ 7 \ 7$	
UF1/0, /		
N 2-PLCS P H H H H H H H H	Dim. Inches Millimeter Minimum Maximum Minimum Maximum Notes A 1.180 1.195 29.97 30.35 C .027 .037 0.69 0.94 E .350 .370 8.89 9.40 F 1.490 1.510 37.85 38.35 G .695 .715 17.65 18.16 H .088 .098 2.24 2.49 J .240 .260 6.10 6.60 K .115 .135 2.92 3.43 L .460 .480 11.68 12.19 M .065 .085 1.65 2.16 N .151 .161 3.84 4.09 Dia. P .015 .025 0.38 0.64	
Note: Baseplate Common with Pin 2 Microsemi Working Peak Repetit	tive Peak	
Catalog Number Reverse Voltage Reverse UFT7010* 100V 11 UFT7015* 150V 15 UFT7020* UFT7120* 200V 2 UFT7130* 300V 3 3 UFT7140* 400V 4 4 UFT7250* UFT7150* 500V 5 UFT7260* 600V 6 6 UFT7270* 700V 7 7	 Voltage Ultra Fast Recovery 175°C Junction temperature V VRRM 100 to 800 Volts V 2 X 35 Amp current rating V ROHS Compliant 	
Electrical Characteristics		
UFT70UFT70UFTAverage forward current per pkg F(AV)70A70AAverage forward current per leg F(AV)35A35DCase TemperatureTC148°C142Maximum surge current per leg FSM700A600Max peak forward voltage per legVFM.95V1.20Max reverse recovery time per legtrr50ns60rMax peak reverse current per leg RM	A 70A Square Wave A 35A Square Wave °C 138°C R Θ JC = 1.0°C/W DA 500A 8.3 ms, half sine, TJ = 175°C DV 1.35V IFM = 35A: TJ = 25°C* ns 75ns 1/2A, 1A, 1/4A, TJ = 25°C WA	
*Pulse test: Pulse width 300µsec, Duty cycle 2%		
Thermal and Mechanical Characteristics		
Storage temp rangeTSTGOperating junction temp rangeTJMax thermal resistance per legRØJCMax thermal resistance per pkgRØJCTypical thermal resistance (greased)RØCSMounting TorqueWeight	-55°C to 175°C -55°C to 175°C 1.0°C/W Junction to case 0.5°C/W Junction to case 0.3°C/W Case to sink 10 inch pounds maximum 0.3 ounce (8.4 grams) typical	



UFT70

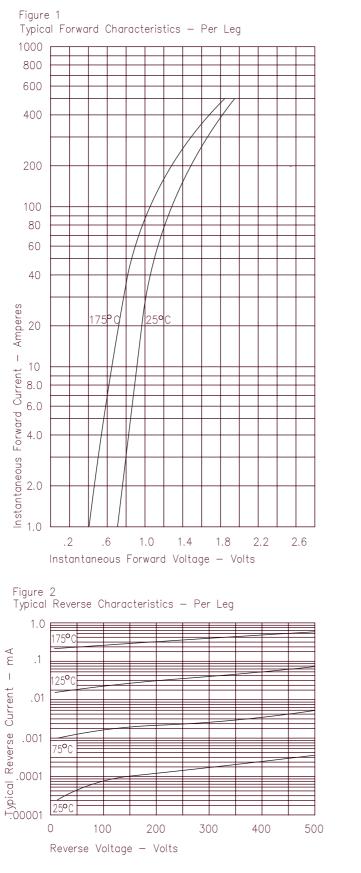




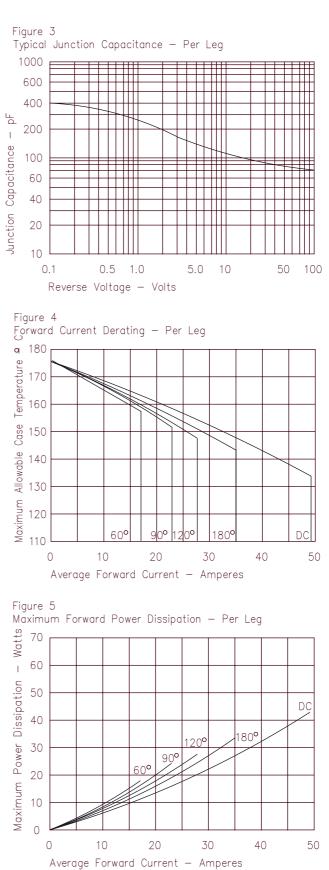


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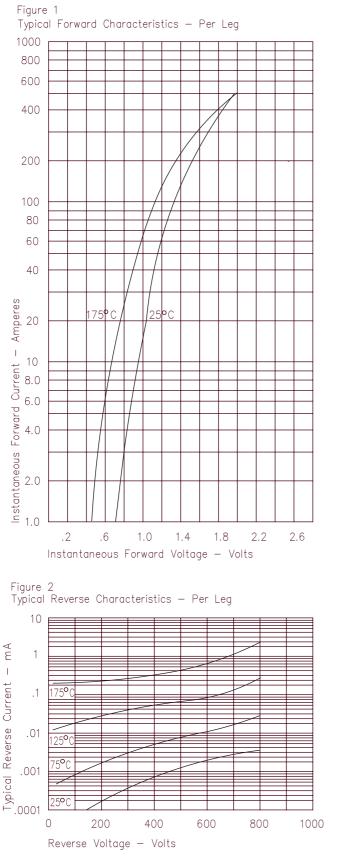


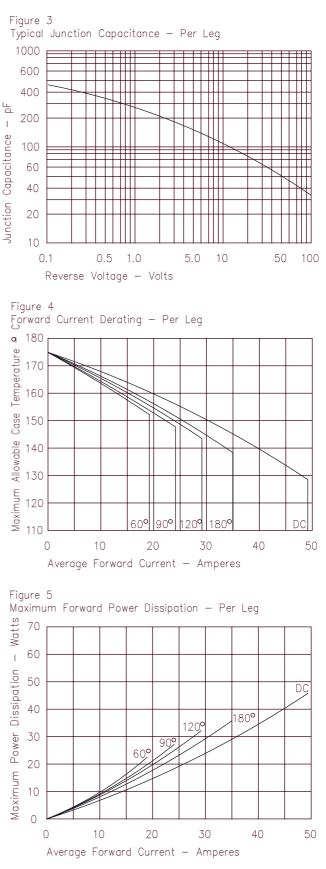




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